

In the Claims:

Please enter the following amended claims 1, 13 and 20:

1. (Once Amended) A structure comprising:

a substrate having a top surface for receiving a die;

B1 a conductor patterned on said top surface of said substrate, said conductor having a first terminal and a second terminal, each of said first and second terminals situated on said top surface of said substrate, said first terminal of said conductor being adapted for connection to a first substrate signal bond pad, said first substrate signal bond pad situated on said top surface of said substrate and said second terminal of said conductor being adapted for connection to a first die signal bond pad, said first die signal bond pad situated on said top surface of said substrate;

a printed circuit board attached to a bottom surface of said substrate;

at least one via in said substrate;

said at least one via providing an electrical connection between a second die signal bond pad and said printed circuit board.

13. (Once Amended) A structure comprising:

a substrate having a top surface for receiving a die;

B2 a conductor patterned within said substrate, said conductor comprising an inductor, said conductor having a first terminal and a second terminal, each of said first and second terminals situated on said top surface of said substrate, a first substrate signal bond pad being said first terminal of said conductor and a second substrate signal bond pad being said second terminal of said conductor;

a printed circuit board attached to a bottom surface of said substrate;

at least one via in said substrate;

said at least one via providing an electrical connection between a die signal bond pad and
said printed circuit board.

20. (Once amended) The structure of claim 19 wherein said conductor is a solenoid

inductor.